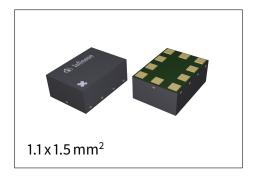


DPDT Antenna Cross Switch

Features

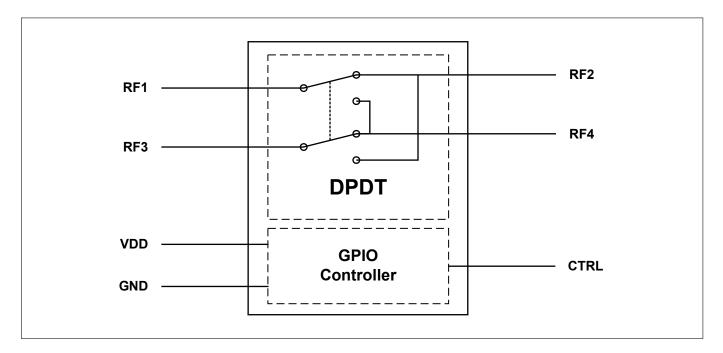
- RF CMOS DPDT antenna cross switch with power handling capability of up to 37 dBm
- Suitable for multi-mode LTE and WCDMA multi antenna applications
- Ultra-low insertion loss and harmonics generation
- 0.1 to 6.0 GHz coverage
- High port-to-port-isolation
- No decoupling capacitors required if no DC applied on RF lines
- General Purpose Input-Output (GPIO) Interface
- Small form factor 1.1mm x 1.5mm
- No power supply blocking required
- High EMI robustness
- RoHS and WEEE compliant package



Product Validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Block diagram



DPDT Antenna Cross Switch

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Table of Contents

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DPDT Antenna Cross Switch

Features

1 Features

- RF CMOS DPDT antenna cross switch with power handling capability of up to 37 dBm
- Suitable for multi-mode LTE and WCDMA multi antenna applications
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- High EMI robustness
- RoHS and WEEE compliant package



Description

The BGSX22G5A10 RF MOS switch is specifically designed for LTE and WCDMA triple antenna applications. This DPDT offers low insertion loss and low harmonic generation paired with high isolation between RF ports.

The switch is controlled via a GPIO interface. The on-chip controller allows power-supply voltages from 1.65V to 3.4V.

The switch features direct-connect-to-battery functionality and DC-free RF ports. Unlike GaAs technology, external DC blocking capacitors at the RF Ports are only required if DC voltage is applied externally. The BGSX22G5A10 RF Switch is manufactured in Infineon's patented MOS technology, offering the performance of GaAs with the economy and integration of conventional CMOS including the inherent higher ESD robustness. The device has a very small size of only 1.1 x 1.5mm² and a maximum thickness of 0.55mm.



Product Name	Marking	Package
BGSX22G5A10	X5	ATSLP-10-50
		ATSLP-10-2



DPDT Antenna Cross Switch

Maximum Ratings

2 Maximum Ratings

Parameter	Symbol		Values		Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Frequency Range	f	0.1	-	6.0	GHz	1)	
Supply voltage ²⁾	V _{DD}	-0.5	-	3.6	V	-	
Storage temperature range	T _{STG}	-55	-	150	°C	-	
Junction temperature	Tj	-	-	125	°C	-	
RF input power at all RF ports	P _{RF}	-	-	39	dBm	VSWR 1:1, 12.5% Duty Cycle	
ESD capability, CDM ³⁾	V _{ESD_CDM}	-1	-	+1	kV		
ESD capability, HBM ⁴⁾	V _{ESD_HBM}	-1	-	+1	kV		
ESD capability, system level ⁵⁾	V _{ESD_RF}	-8	-	+8	kV	RF versus system GND, wit	
						27 nH	
Thermal resistance junction -	R _{thJS}	-	-	60	K/W	-	
soldering point							
Maximum DC-voltage on RF-	V _{RFDC}	0	-	0	V	No DC voltages allowed on Rf	
Ports and RF-Ground						Ports	
GPIO control voltage levels	V _{Ctrlx}	-0.7	-	V _{DD} +0.7	V	-	
				(max.			
				3.6V)			

Table 1: Maximum Ratings Table at $T_A = 25 \,^{\circ}C$, unless otherwise specified

¹⁾Switch has a lowpass response. For higher frequencies, losses have to be considered for their impact on thermal heating. The DC voltage at RF ports VRFDC has to be 0V.

²⁾Note: Consider potential ripple voltages on top of V_{DD} . Including RF ripple, V_{DD} must not exceed the maximum ratings: $V_{DD} = V_{DC} + V_{Ripple}$. Furthermore, high pulse voltages at V_{DD} pin will cause the ESD structure to trigger.

³⁾ Field-Induced Charged-Device Model ANSI/ESDA/JEDEC JS-002. Simulates charging/discharging events that occur in production equipment and processes. Potential for CDM ESD events occurs whenever there is metal-to-metal contact in manufacturing.

. ⁴⁾Human Body Model ANSI/ESDA/JEDEC JS-001 (R=1,5 kΩ, C=100 pF).

 $^{5)}$ IEC 61000-4-2 (R=330 $\varOmega,$ C=150 pF), contact discharge.

Warning: Stresses above the max. values listed here may cause permanent damage to the device. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. Exposure to conditions at or below absolute maximum rating but above the specified maximum operation conditions may affect device reliability and life time. Functionality of the device might not be given under these conditions.



DPDT Antenna Cross Switch

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Operation Ranges

3 Operation Ranges

Symbol Values Unit Note / Test Condition Parameter Min. Тур. Мах. Supply voltage 1.65 3.4 ٧ V_{DD} _ _ _ 200 Supply current 55 μΑ _ I_{DD} GPIO control voltage high 1.35 _ $V_{DD} + 0.3$ ٧ V_{Ctrl_H} _ (max. 3.6V) GPIO control voltage low 0.45 V _ -0.3 _ V_{Ctrl_L} GPIO control input capacitance _ _ 2 рF _ C_{Ctrl} Ambient temperature 85 °C T_A -40 25 _

Table 2: Operation Ranges at $T_A = -40$ °C...85 °C, $P_{IN} = 0$ dBm, Supply Voltage $V_{DD} = 1.65$ V ... 3.4V, unless otherwise specified

Table 3: RF Input Power

Parameter	Symbol	Values		Unit	Note / Test Condition	
		Min.	Тур.	Max.		
RF input power	P _{RF}	-	-	37	dBm	VSWR 1:1, 12.5% Duty Cycle

DPDT Antenna Cross Switch



RF Characteristics

4 RF Characteristics

Table 4: RF Characteristics at $T_A = 25$ °C, $P_{IN} = 0$ dBm, Supply Voltage $V_{DD} = 2.8$ V, unless otherwise specified

Parameter	Symbol		Values		Unit	Note / Test Condition
		Min.	Тур.	Max.		
Insertion Loss ¹⁾						•
		-	0.28	0.35	dB	699 to 960MHz
		-	0.37	0.5	dB	1710 to 2200MHz
All RF ports		-	0.45	0.6	dB	2300 to 2690MHz
All RF ports	IL	-	0.60	1.0	dB	3300 to 4200MHz
		-	0.80	1.2	dB	4400 to 5000MHz
		-	1.10	1.5	dB	5150 to 5925MHz
Return Loss ¹⁾	·	·	·	÷		· · · · · · · · · · · · · · · · · · ·
		19	24	-	dB	699 to 960MHz
		15	17	-	dB	1710 to 2200MHz
All RF ports	RL	14	16	-	dB	2300 to 2690MHz
	KL	12	15	-	dB	3300 to 4200MHz
		10	13	-	dB	4400 to 5000MHz
		7	10	-	dB	5150 to 5925MHz

¹⁾Measured on application board without any external matching components.

Table 5: RF Characteristics at T_A = -40 °C...85 °C, P_{IN} = 0 dBm, Supply Voltage V_{DD} = 1.65V ... 3.4V, unless otherwise specified

Parameter	Symbol		Values		Unit	Note / Test Condition
		Min.	Тур.	Max.		
Insertion Loss ¹⁾	I.	I	I			
		-	0.28	0.4	dB	699 to 960MHz
		-	0.37	0.6	dB	1710 to 2200MHz
All DE parte		-	0.45	0.7	dB	2300 to 2690MHz
All RF ports	IL	-	0.60	1.1	dB	3300 to 4200MHz
		-	0.80	1.3	dB	4400 to 5000MHz
		-	1.10	1.7	dB	5150 to 5925MHz
Return Loss ¹⁾	·					•
		19	24	-	dB	699 to 960MHz
		14	17	-	dB	1710 to 2200MHz
All RF ports	DI	13	16	-	dB	2300 to 2690MHz
	RL	10	15	-	dB	3300 to 4200MHz
		9	13	-	dB	4400 to 5000MHz
		6	10	-	dB	5150 to 5925MHz

¹⁾Measured on application board without any external matching components.

RF Characteristics



Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Isolation ¹⁾	· · · ·					•
		47	49	-	dB	699 to 960MHz
State 1	ISO	41	43	-	dB	1710 to 2200MHz
RF1-RF3, RF2-RF4		39	41	-	dB	2300 to 2690MHz
	150	37	39	-	dB	3300 to 4200MHz
		36	39	-	dB	4400 to 5000MHz
		34	38	-	dB	5150 to 5925MHz
Isolation ¹⁾						•
		41	44	-	dB	699 to 960MHz
State 2		35	37	-	dB	1710 to 2200MHz
RF1-RF3, RF2-RF4	100	33	35	-	dB	2300 to 2690MHz
	ISO	31	33	-	dB	3300 to 4200MHz
		31	33	-	dB	4400 to 5000MHz
		33	35	-	dB	5150 to 5925MHz
Isolation ¹⁾		I	I	I		
		56	58	-	dB	699 to 960MHz
State 1		49	52	-	dB	1710 to 2200MHz
RF1-RF4, RF3-RF2		48	50	-	dB	2300 to 2690MHz
	ISO	44	49	-	dB	3300 to 4200MHz
		41	46	-	dB	4400 to 5000MHz
		38	43	-	dB	5150 to 5925MHz
Isolation ¹⁾						
		39	41	-	dB	699 to 960MHz
State 2		32	34	-	dB	1710 to 2200MHz
RF1-RF2, RF3-RF4		31	33	-	dB	2300 to 2690MHz
	ISO	28	30	-	dB	3300 to 4200MHz
		28	29	-	dB	4400 to 5000MHz
		29	31	-	dB	5150 to 5925MHz
Harmonic Generation	I					
H2		-	-85	-65	dBm	25 dBm, 50 Ω, CW mode
H3		-	-90	-75	dBm	25 dBm, 50 Ω, CW mode
H2, GSM LB		-	-70	-55	dBm	35 dBm, 50 Ω, 50% duty cycle
H3, GSM LB	P _{Harm}	_	-60	-55	dBm	35 dBm, 50 Ω, 50% duty cycle
H2, GSM HB			-70	-55	dBm	33 dBm, 50 Ω, 50% duty cycle
H3, GSM HB		-	-60	-55	dBm	33 dBm, 50 Ω, 50% duty cycle
Intermodulation Distortion IME)2					
IIP2, low	IIP2,l	110	125	_	dBm	
IIP2, high	IIP2,h	110	125	-	dBm	IIP2 conditions, Tab. 7
Intermodulation Distortion IME	,	110	130		ubiii	
	IIP3	65	80	_	dBm	IIP3 conditions Tab 9
IIP3 ¹⁾ Measured on application board			80	-	dBm	IIP3 conditions, Tab. 8

Table 6: RF Characteristics at T_A = -40 °C...85 °C, P_{IN} = 0 dBm, Supply Voltage V_{DD}= 1.65V ... 3.4V, unless otherwise specified



RF Characteristics

Table 7: IIP2 conditions table

Band	In-Band Frequency	Blocker Frequency 1	Blocker Power 1	Blocker Frequency 2	Blocker Power 2
	[MHz]	[MHz]	[dBm]	[MHz]	[dBm]
Band 1 Low	2140	1950	24	190	-10
Band 1 High	2140	1950	24	4090	-10
Band 5 High	880	835	24	1715	-10
Band 7 Low	2655	2535	24	120	-10
Band 7 High	2655	2535	24	5190	-10

Table 8: IIP3 conditions table

Band	In-Band Frequency	Blocker Frequency 1	Blocker Power 1	Blocker Frequency 2	Blocker Power 2
	[MHz]	[MHz]	[dBm]	[MHz]	[dBm]
Band 1 Low	2140	1950	24	95	-10
Band 1 Mid	2140	1950	24	1760	-10
Band 1 High	2140	1950	24	6040	-10
Band 5 Low	880	835	24	22.5	-10
Band 5 Mid	880	835	24	790	-10
Band 5 High	880	835	24	2550	-10
Band 7 Low	2655	2535	24	60	-10
Band 7 Mid	2655	2535	24	2415	-10
Band 7 High	2655	2535	24	7725	-10



RF Characteristics

Parameter	Symbol		Values			Note / Test Condition
		Min.	Typ. Max.			
Switching Time	ľ					
RF Rise Time	t _{RT}	-	-	1	μs	10 % to 90 % RF signal
Switching Time	t _{ST}	-	3	4	μs	50 % Ctrl signal to 90 % RF signal
Switching Time	t _{ST}	-	2	3	μs	50 % Ctrl signal to 90 % RF signal, Supply Voltage V _{DD} = 2.6 V 3.4 V
Power Up Settling Time	t _{Pup}	-	10	25	μs	After power down mode

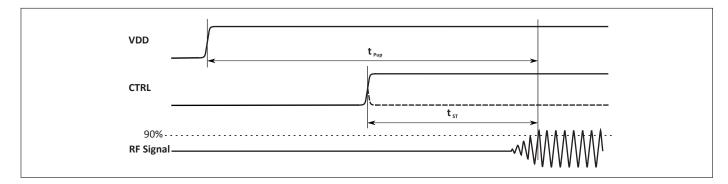


Figure 1: Power Up Settling Time and Switching Time

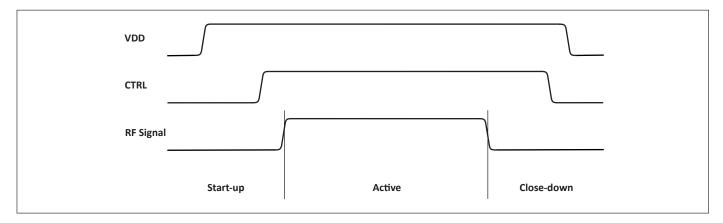


Figure 2: Power On and Off Sequence

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Application Information

5 Modes of Operation

Table 10: Modes of Operation (Truth Table)

		Control Input
State	Mode	CTRL
1	RF1 - RF2	0
I	RF3 - RF4	0
2	RF1 - RF4	1
2	RF3 - RF2	

6 Application Information

Pin Configuration and Function

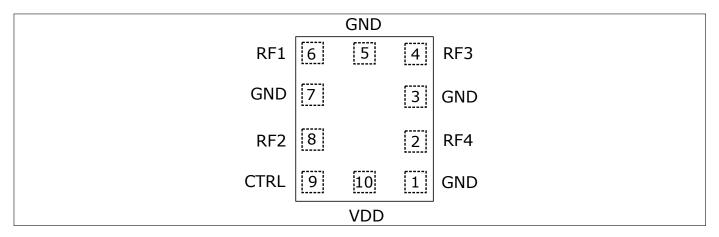


Figure 3: BGSX22G5A10 Pin Configuration (top view)

Table 11: Pin Definition and Function

Pin No.	Name	Function
1	GND	DC ground
2	RF4	RF port 4
3	GND	RF ground
4	RF3	RF port 3
5	GND	RF ground
6	RF1	RF port 1
7	GND	RF ground
8	RF2	RF port 2
9	CTRL	GPIO control pin
10	VDD	Power supply

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Package Information

7 Package Information

Table 12: Mechanical Data

Parameter	Symbol	Value	Unit	
X-Dimension	X	1.1 ± 0.1	mm	
Y-Dimension	Y	1.5 ± 0.1	mm	
Size	Size	1.65	mm ²	
Height	Н	0.55 ± 0.1	mm	

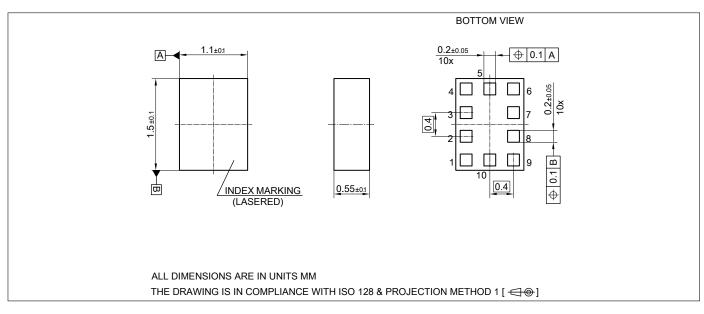


Figure 4: ATSLP-10-50/-2 Package Outline (top, side and bottom views)

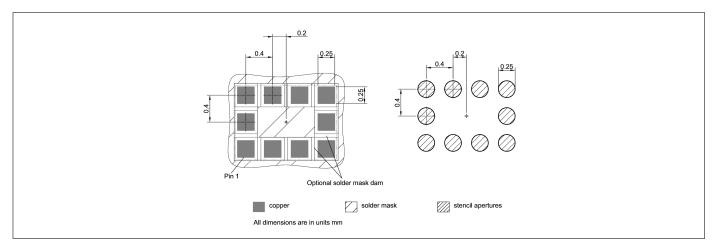


Figure 5: Footprint Recommendation

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Package Information

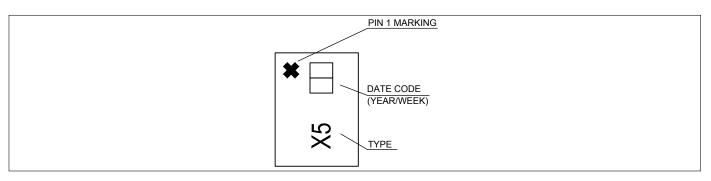


Figure 6: Marking Specification (top view): Date code digits Y and W defined in Table 13/14

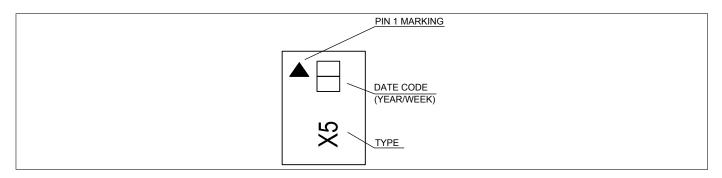


Figure 7: ATSLP-10-2 Marking Specification (top view): Date code digits Y and W defined in Table 13/14



Package Information

Table 15: fear date code marking - digit f						
Year	"Y"	Year	"Y"	Year	"Y"	
2010	0	2020	0	2030	0	
2011	1	2021	1	2031	1	
2012	2	2022	2	2032	2	
2013	3	2023	3	2033	3	
2014	4	2024	4	2034	4	
2015	5	2025	5	2035	5	
2016	6	2026	6	2036	6	
2017	7	2027	7	2037	7	
2018	8	2028	8	2038	8	
2019	9	2029	9	2039	9	

Table 13: Year date code marking - digit "Y"

Table 14: Week date code marking - digit "W"

Week	"W"	Week	"W"	Week	"W"	Week	"W"	Week	"W"
1	A	12	N	23	4	34	h	45	v
2	В	13	Р	24	5	35	j	46	x
3	С	14	Q	25	6	36	k	47	у
4	D	15	R	26	7	37	l	48	z
5	E	16	S	27	а	38	n	49	8
6	F	17	Т	28	b	39	р	50	9
7	G	18	U	29	с	40	q	51	2
8	н	19	V	30	d	41	r	52	3
9	J	20	W	31	e	42	s	53	М
10	к	21	Y	32	f	43	t		
11	L	22	Z	33	g	44	u		



Package Information

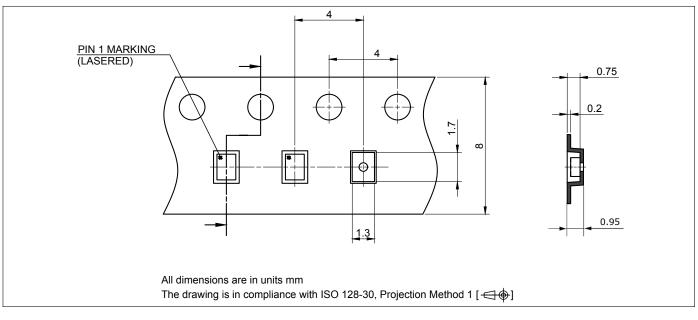


Figure 8: ATSLP-10-50 Carrier Tape

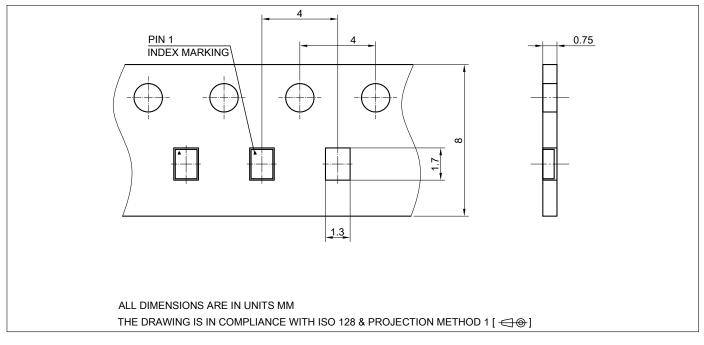


Figure 9: ATSLP-10-2 Carrier Tape

Revision History				
Page or Item Subjects (major changes since previous revision)				
Revision 8.6, 2020-04-15				
all	New template			

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